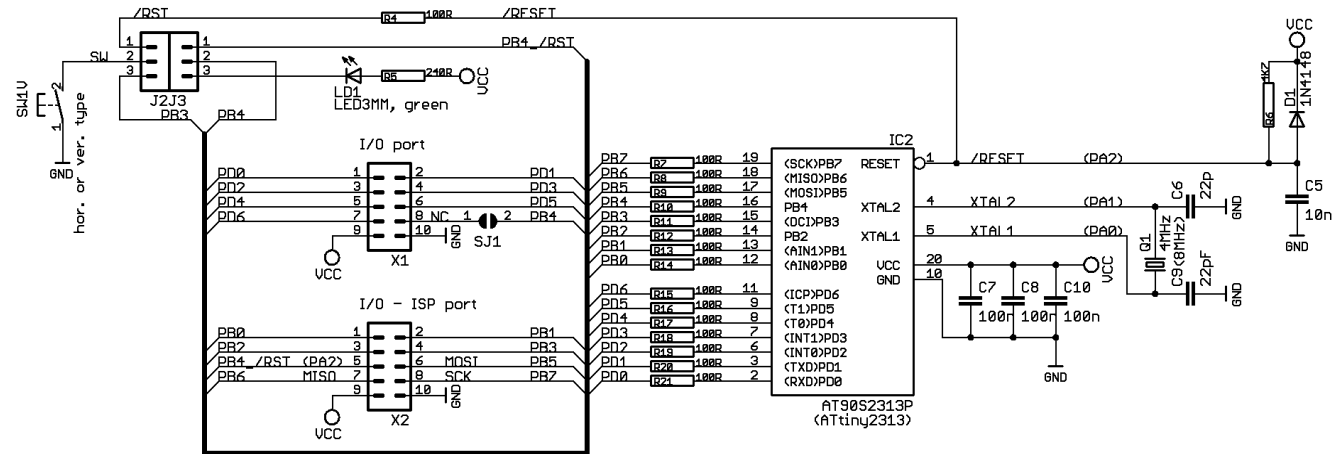
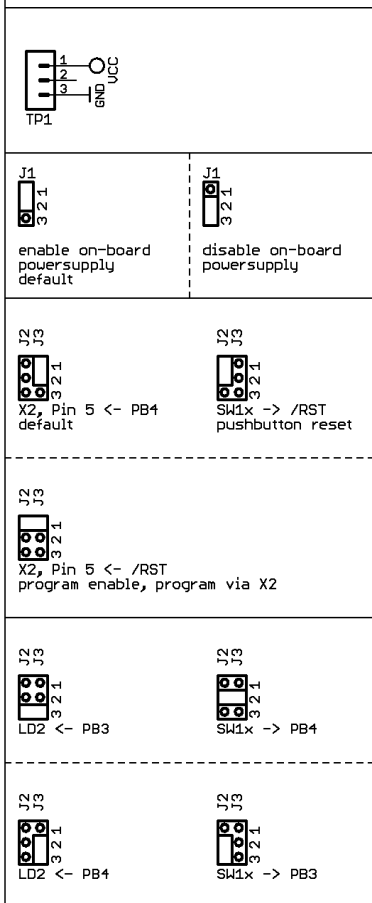
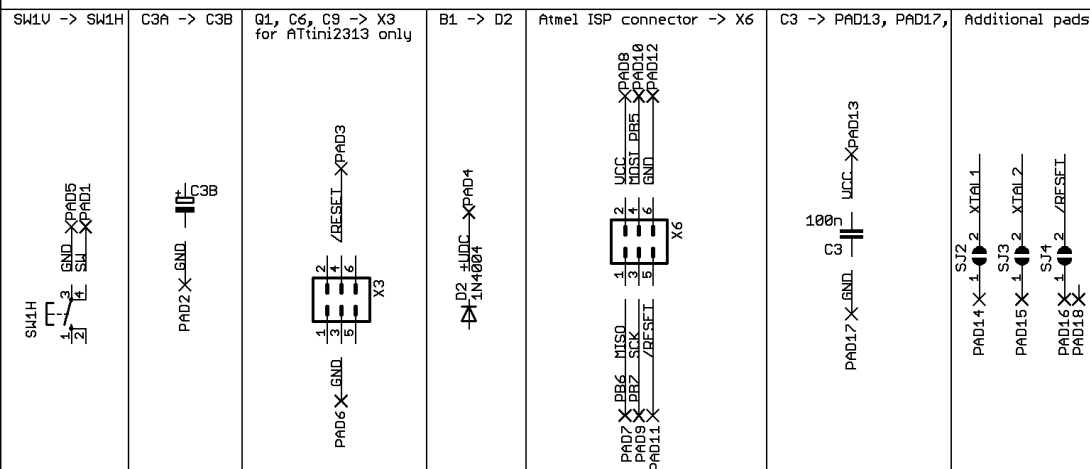


Jumper settings:



Assembling options, additional pads:



0p, 100M parts not assembled.
 Board useable for AT90S2313 or ATtiny2313 in DIP package.
 All values shown for UCC=3V3 and IC2=AT90S2313, for other type of MCU and UCC adjust values according to MCU datasheet.

| | |
|---|------------|
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| TITLE: 021LK001 | |
| Document Number: | REV: |
| eLAB - AT90S2313/ATtiny2313 mcu board | 1.1 |
| Date: 16.11.2004 11:09:16 | Sheet: 1/1 |